

YGRP322711-ATC3

Dual Wavelength SMD Type Emitter

Features

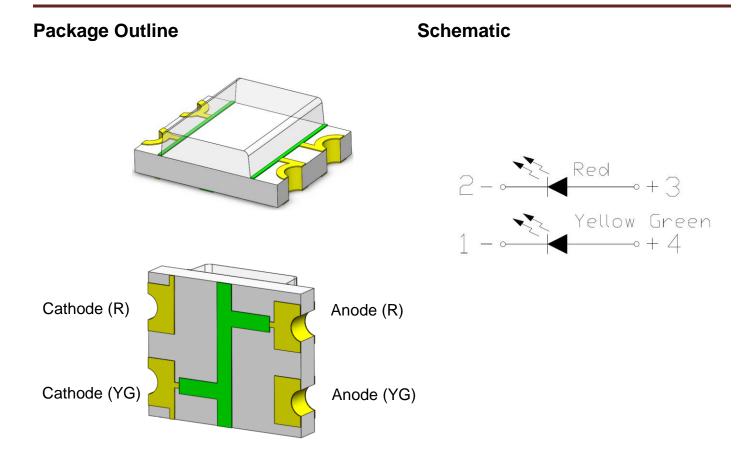
- Top view 3227 package
- Viewing Angle = $\pm 65^{\circ}$
- Compatible with infrared and vapor phase reflow solder process
- High reliability
- Dual dominant wavelength (YG=570nm , R=620nm)
- RoHS compliance

Applications

- Optical indicator.
- Switch and Symbol Display.

Description

The YGRP322711-ATC3 is a double LED housed in a miniature SMD package. The device has a dominant wavelength of 570nm and 620nm LED.





Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
1_	Continuous Forward Current	YG	25	mA	
IF	Commodes Forward Current	R	25	mA	
1	Deels Ferryard Current	YG	80		
IFP	Peak Forward Current		80	mA	1
V _R	Reverse Voltage		5	V	
T _{opr}	Operating Temperature		-40 ~ +85	0C	
T _{stg}	Storage Temperature		-40 ~ +100	0 C	
T _{sol}	Soldering Temperature		260	0 C	2
Р	Power Dissipation at(or below) 25°C Free Air		60		
PD	Temperature	R	60	mW	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics (Yellow Green)

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I _F =20mA	28.5	-	112.5	mcd	3
λ _D	Dominant Wavelength	I _F =20mA	567.5	-	576.5	nm	4
θ1/2	Angle of Half Intensity	I⊧=20mA	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I _F =20mA	1.6	-	2.4	V	
I _R	Reverse Current	V _R =5V	-	-	1	μA	



Optical Characteristics (Red)

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I _F =20mA	45.0	-	180	mcd	3
λD	Dominant Wavelength	I _F =20mA	615	-	630	nm	
θ1/2	Angle of Half Intensity	I _F =20mA	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I _F =20mA	1.6	-	2.4	V	
IR	Reverse Current	V _R =5V	-	-	1	μA	

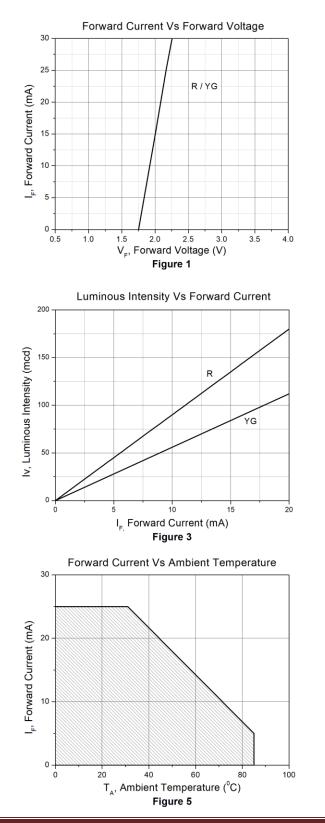
Notes:

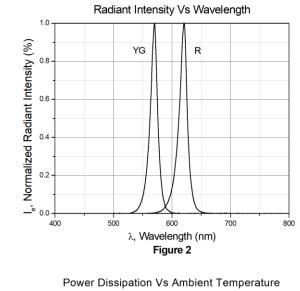
- 1. I_{FP} Conditions--Pulse Width $\leq \,$ 100 $\!\mu s$ and Duty $\leq \,$ 10%.
- 2. Soldering time ≤ 10 seconds.

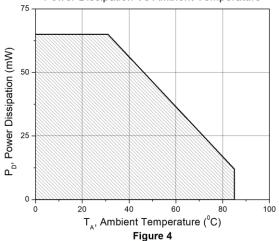


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Typical Characteristic Curves

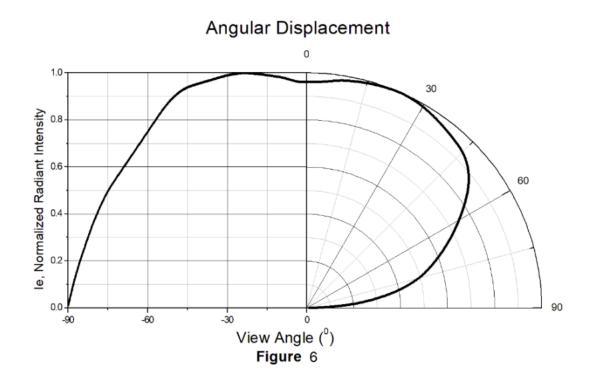






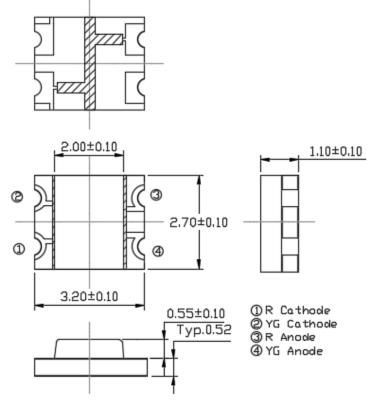


Typical Characteristic Curves



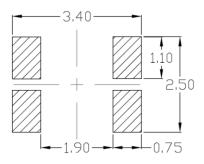


Package Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.

Recommended Soldering Mask All dimensions are in mm, unless otherwise stated

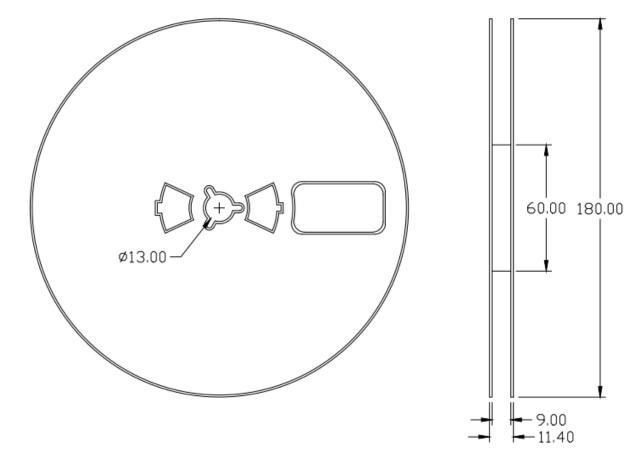


Note: Tolerance unless mentioned is ±0.1mm.

Ordering Information

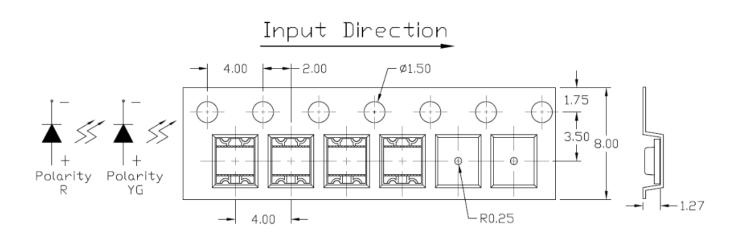
Part Number	Description	Quantity
YGRP322711-ATC3	Tape & Reel	3000 pcs





Reel Dimension All dimensions are in mm, unless otherwise stated

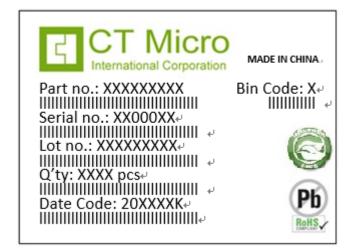
Tape Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.



Label Form Specification



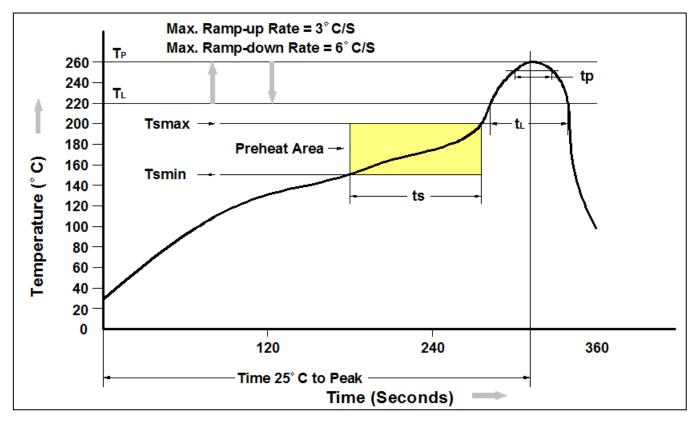
Part no: CTM Production Number Serial no: Production Number Lot no: Lot number Q'ty: Packing Quantity Date Code: Manufacture Date Bin Code: Iv Ranks MADE IN CHINA: Production Place

Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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